

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)



Docket Number (Optional)

NE-70085US

Application Number

10/613,069

Applicant(s)

Hiroyuki KUNISHIMA, et al.

Filing Date

July 7, 2003

Group Art Unit

Not Yet Assigned

PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

ak		T. Takewaki, et al., "Formation of grain-grain copper interconnects by a low-energy ion bombardment process for high-speed ULSIs", <u>Materials Chemistry and Physics</u> 41 (1995) pp. 182-191.

EXAMINER

[Signature]

DATE CONSIDERED

11/08/04

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.